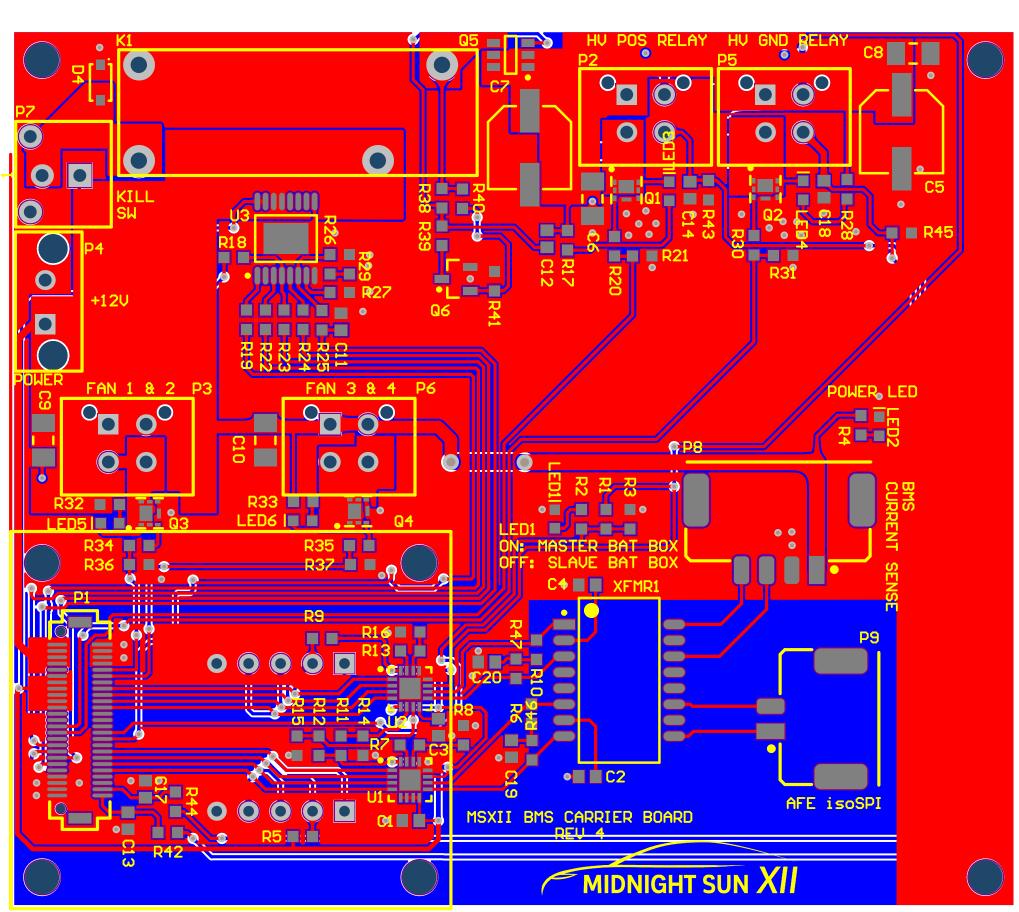
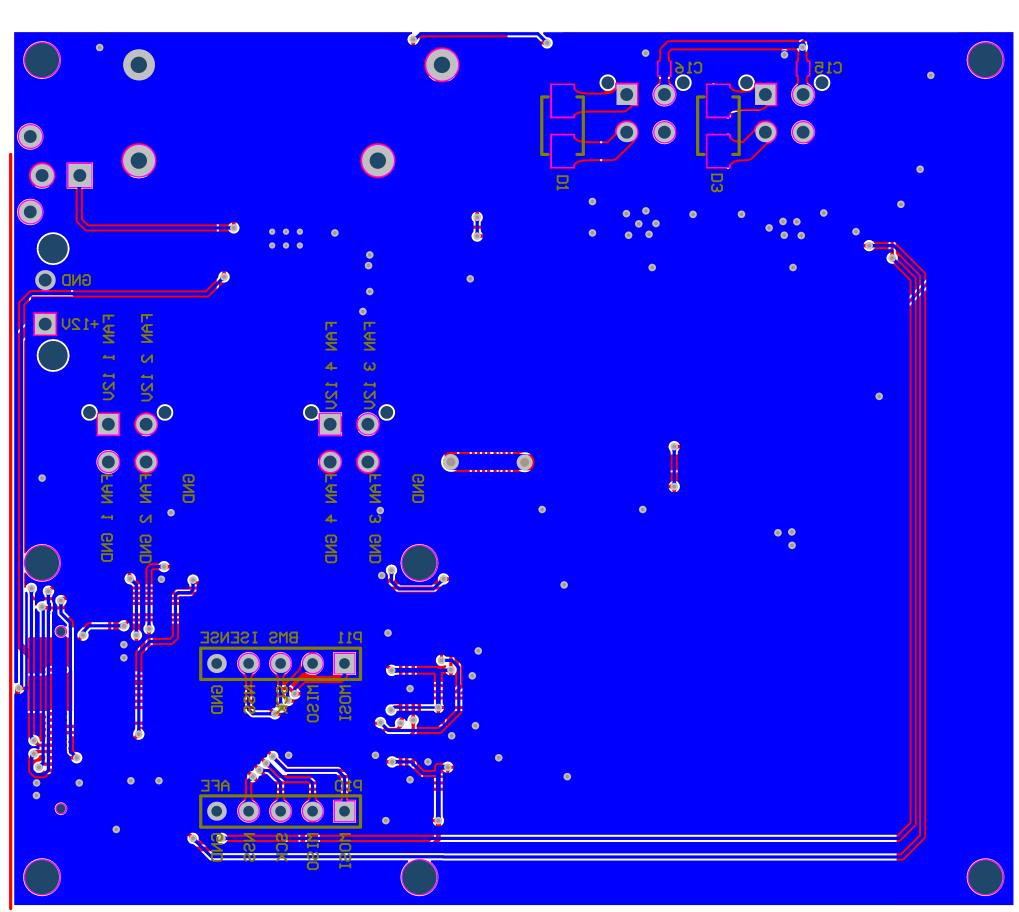


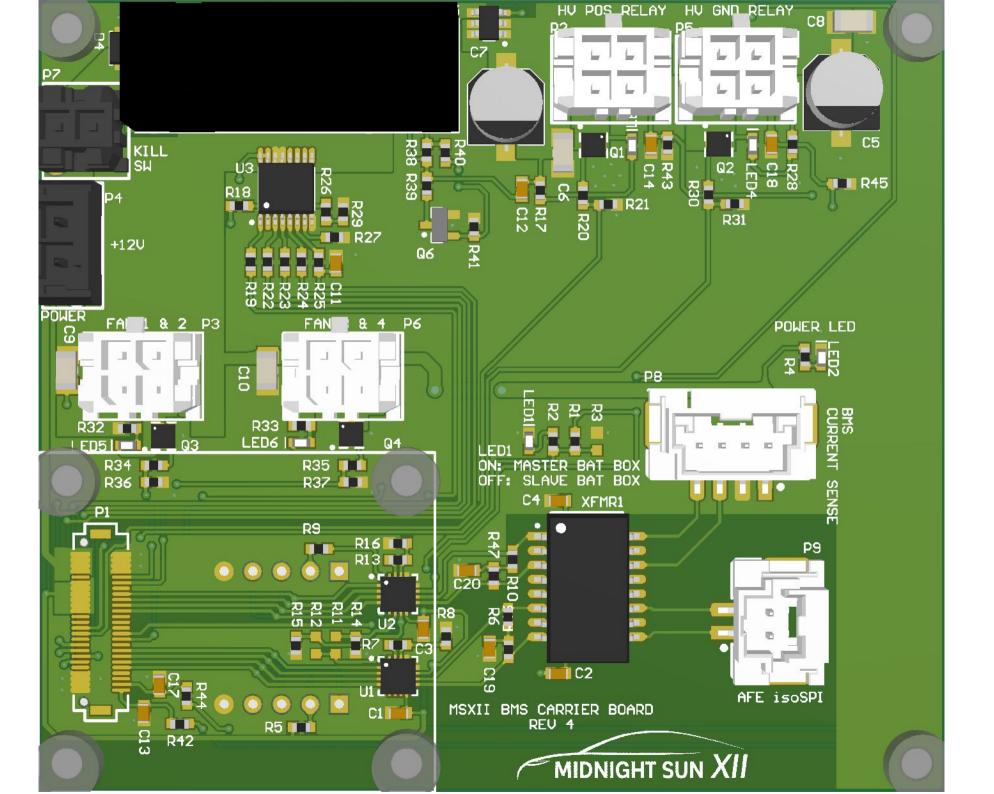
Bill of Materials					
Project:	BMS_Carrier_Board.PrjPcb				
Revision:	4.0				
Project Lead:	Aashmika Mali & Liam Hawkins				
Generated On:	2019-04-06 3:18:34 PM				
Production Quantity:	1				
Currency	CAD				
Total Parts Count:	93				



LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Quantity	Supplier Subtotal 1	
CAP CER 0.1UF 50V 10% X7R 0603	C1, C3, C11, C13, C17	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.21	5	\$	1.07
CAP CER 20PF 50V ±5% C0G/NP0 0603	C2, C4	Murata	GRM1885C1H200JA01D	Digi-Key	490-1410-1-ND	0.13	2	\$	0.27
CAP ALUM 47UF 20% 35V SMD	C5, C7	Panasonic	EEE1VA470WP	Digi-Key	PCE3961CT-ND	0.55	2	\$	1.10
CAP CER 2.2UF 100V ±20% X7R 1206	C6, C8, C9, C10	Murata	GRM31CR72A225MA73L	Digi-Key	490-12773-1-ND		4		
CAP CER 4.7UF 25V 10% X5R 0603	C12	<u>Murata</u>	GRM188R61E475KE11D	Digi-Key	490-7203-1-ND	0.5	1	\$	0.50
CAP CER 10nF 50V 5% X7R 0603	C14, C15, C16, C18, C19, C20	<u>KEMET</u>	C0603C103J5JACTU	Digi-Key	399-13384-1-ND	0.48	6	\$	2.89
DIODE SCHOTTKY 60V 3A SMA	D1, D3	<u>Diodes</u>	B360A-13-F	Digi-Key	B360A-FDICT-ND	0.55	2	\$	1.10
DIODE GEN PURP 100V 300MA SOD123	D4	Diodes Zetex	1N4148WQ-7-F	Digi-Key	<u>1N4148WQ-7-FDICT-</u> <u>ND</u>	0.29	1	\$	0.29
RELAY SPST 12V 8A OMRON	K1	<u>Omron</u>	G6RN-1ADC12	Digi-Key	<u>Z2346-ND</u>	5.45	1	\$	5.45
LED RED CLEAR 2V 0603	LED1	Wurth Electronics	150060RS75000	Digi-Key	732-4978-1-ND	0.19	1	\$	0.19
LED GREEN CLEAR 2V 0603	LED2	Wurth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.19	1	\$	0.19
LED YELLOW CLEAR 2.1V 0603	LED3, LED4, LED5, LED6	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.19	4	\$	0.75
CONN 50POS Bergstak Plug 0.02"	P1	Amphenol FCI	10132797-055100LF	Digi-Key	609-5226-1-ND	1.87	1	\$	1.87
CONN 4POS MICRO-FIT 3mm	P2, P3, P5, P6	Molex	0430450427	Digi-Key	WM10667-ND	1.79	4	\$	7.17
CONN 2POS ULTRA-FIT 0.138"	P4	Molex	1722861302	Digi-Key	WM11673-ND	1.95	1	\$	1.95
CONN 2POS MICRO-FIT 3mm	P7	Molex	0430450227	Digi-Key	WM10657-ND	1.12	1	\$	1.12
CONN 4POS DURA-CLIK 0.079"	P8	Molex	560020-0420	Digi-Key	WM10864CT-ND	2.22	1	\$	2.22
CONN 2POS DURA-CLIK 0.079" VERT	P9	Molex	560020-0220	Digi-Key	WM10862CT-ND	1.04	1	\$	1.04
MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q1, Q2, Q3, Q4	International Rectifier	IRLHS6342TRPBF	Digi-Key	IRLHS6342TRPBFCT- ND	0.9	4	\$	3.59
MOSFET P-CH 30V 4A 1.6W SOT-23-6	Q5	STMicroelectronics	STT4P3LLH6	Digi-Key	497-15521-1-ND	0.87	1	\$	0.87
MOSFET N-CH 60V 310MA SOT23	Q6	Diodes	DMN65D8L-7	Digi-Key	DMN65D8L-7DICT-ND	0.25	1	\$	0.25
RES 0.0 OHM 1/4W 0603	R1, R14, R15, R40	Vishay Dale	CRCW06030000Z0EAHP	Digi-Key	541-0.0SBCT-ND	0.23	4	\$	0.91
RES 604 OHM 1% 1/10W 0603	R2, R8, R16	<u>Yageo</u>	RC0603FR-07604RL	Digi-Key	311-604HRCT-ND	0.13	3	\$	0.40
RES 4.7K OHM 1% 1/10W 0603	R4, R17, R18, R19, R22, R23, R24, R25, R27, R28, R32, R33	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.03	12	\$	0.39
RES 2K OHM 1% 1/10W 0603	R5, R9, R29	<u>Yageo</u>	RC0603FR-072KL	Digi-Key	311-2.00KHRCT-ND	0.13	3	\$	0.40
RES 62 OHM 0.1% 1/10W 0603	R6, R10, R46, R47	<u>Panasonic</u>	ERA3AEB620V	Digi-Key	P62DBCT-ND	0.47	4	\$	1.87
RES 1.4k OHM 1% 1/10W 0603	R7, R13	<u>Yageo</u>	RC0603FR-071K4L	Digi-Key	311-1.40KHRCT-ND	0.13	2	\$	0.27
RES 22.1 OHM 1% 1/10W 0603	R20, R30, R34, R35	<u>Yageo</u>	RC0603FR-0722R1L	Digi-Key	311-22.1HRCT-ND	0.13	4	\$	0.54
RES 10K OHM 1% 1/10W 0603	R21, R31, R36, R37, R41, R43, R45	Yageo Phycomp	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	7	\$	0.94
RES 3.3K OHM 1% 1/4W 0603	R26	<u>Panasonic</u>	ERJPA3F3301V	Digi-Key	P3.3KBYCT-ND	0.21	1	\$	0.21
RES 330 OHM 1% 1/10W 0603	R38	TE Connectivity	CRGCQ0603F330R	Digi-Key	A129682TR-ND		1		
RES 1K OHM 5% 1/10W 0603	R39, R42, R44	<u>Yageo</u>	RC0603JR-071KL	Digi-Key	311-1.0KGRCT-ND	0.13	3	\$	0.40
IC ISOSPI COMM INTERFACE LTC6820IUD	U1, U2	Analog Devices / Linear Technology	LTC6820IUD#PBF	Digi-Key	LTC6820IUD#PBF-ND	7.44	2	\$	14.88
IC HSD Dual-Channel 40V 1KOhm	U3	Texas Instruments	TPS2H000BQPWPRQ1	Digi-Key	TPS2H000BQPWPRQ1- ND		1		
IC PULSE XFMR 1CT:1CT 350UH SMD	XFMR1	<u>Bourns</u>	PT61018AAPEL-S	Digi-Key	PT61018AAPEL-SCT- ND	5.13	1	\$	5.13
				L			Total:	\$	60.22







## **Electrical Rules Check Report**

Class	Document	Message
Warning	BMS Carrier - Firmware Contactor	Global Power-Object 3V3 at 2600mil,5100milhas been reduced to local level by presence of
	Control.SchDoc	port at 2800mil,4500mil
Warning	Controller_Board_Interface.SchDoc	Net 3V3 has no driving source (Pin C1-1,Pin C3-1,Pin C15-1,Pin C16-1,Pin P1-40,Pin
		P1-41,Pin P1-42,Pin P1-43,Pin P1-44,Pin P1-45,Pin P2-3,Pin P5-3,Pin R1-1,Pin R5-1,Pin
		R9-1,Pin R11-1,Pin R12-1,Pin R18-2,Pin U1-5,Pin U1-6,Pin U1-7,Pin U1-8,Pin U1-11,Pin
Error	BMS Carrier - Connectors.SchDoc	U1. 16 Pin U2. 5 Pin U2. 8 Pin U2. 11. Pin U2. 16) Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Port
		12V_CONTACTOR_COIL_SW,Port 12V_CONTACTOR_COIL_SW)
Error	BMS Carrier - Battery Relay	Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Port
	Controls.SchDoc	12V_CONTACTOR_COIL_SW,Port 12V_CONTACTOR_COIL_SW,Port
_		HV_GND_RELAY_12V_SW,Port HV_PWR_RELAY_12V_SW)
Error	BMS Carrier - Battery Relay	Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Port
	Controls.SchDoc	HV_GND_RELAY_12V_SW,Port HV_PWR_RELAY_12V_SW)
Error	BMS Carrier - Battery Relay	Net NetD1_1 contains multiple Input Ports (Port HV_PWR_RELAY_GND,Port
	Controls.SchDoc	HV PWR RELAY GND)
Error	BMS Carrier - Battery Relay	Net NetD3_1 contains multiple Input Ports (Port HV_GND_RELAY_GND,Porl
	Controls.SchDoc	HV_GND_RELAY_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net NetLED5_2 contains multiple Input Ports (Port FAN_1_GND,Port FAN_1_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net NetLED6_2 contains multiple Input Ports (Port FAN_2_GND,Port FAN_2_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net PA9_FAN_2_PWM contains multiple Input Ports (Port PA9_FAN_2_PWM,Porl
		PA9 FAN 2 PWM)
Error	BMS Carrier - Fan Controls.SchDoc	Net PA10_FAN_1_PWM contains multiple Input Ports (Port PA10_FAN_1_PWM,Port
		PA10_FAN_1_PWM)
Warning	Controller_Board_Interface.SchDoc	Net PB0_MOSFET_SOFT_START_INPUT has no driving source (Pin P1-17)
Error	BMS Carrier - AFE Interface.SchDoc	Net PB0_MOSFET_SOFT_START_INPUT has only one pin (Pin P1-17)
Warning	BMS Carrier - Battery Relay	Unconnected line (4850mil,2100mil) To (4950mil,2100mil)
	Controls.SchDoc	

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**Design Rules Verification Report**Filename : C:\Users\Aashmika Mali\Documents\First Year\Midnight Sun\hardware\MSXII\_BN

Warnings 0 Rule Violations 99

## Warnings Total 0

Rule Violations	
Clearance Constraint (Gap=0.152mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ( (All) )	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.203mm) (Max=2.54mm) (Preferred=0.203mm) (All)	0
Power Plane Connect Rule(Direct Connect) (Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=5.08mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	99
Silk To Solder Mask (Clearance=0.254mm) (Disabled)(IsPad),(All)	0
Silk to Silk (Clearance=0.254mm) (Disabled)(All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	99

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Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.244mm < 0.254mm) Between Pad C13-1(9.324mm,7.675mm) on Top Layer And Pad
©11/7irfi\(1ifa\): Stolide & 10/25stn 6ti)/ver Constraint: (0.105mm < 0.254mm) Between Pad P1-(4mm,22.05mm) on Multi-Layer And Pad P1-(5.5mm,22.8mm) on Tor
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.254mm) Between Pad P1-(4mm,7.95mm) on Multi-Layer And Pad P1-(5.5mm,7.2mm) on Top
Milyemum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q1-1(48.025mm,57.8mm) on Top Layer And Pad
Minarth PSomer. Waskismer Constraint: (0.047mm < 0.254mm) Between Pad Q1-2(48.025mm,57.15mm) on Top Layer And Pad
Qing(48:025mm,56.5mm) on Top Layer And Pad
Qin/A/Ab/9Soide FMASknShi)ver Constraint: (0.202mm < 0.254mm) Between Pad Q1-3(48.025mm, 56.5mm) on Top Layer And Pad
Q1hB(4Br9Solde,5M4\$kn8h))er Constraint: (0.047mm < 0.254mm) Between Pad Q1-4(49.875mm,56.5mm) on Top Layer And Pad
Q1nfx(4Pr855mer, N/askr9m)er Constraint: (0.047mm < 0.254mm) Between Pad Q1-4(49.875mm, 56.5mm) on Top Layer And Pad
Q1h/(4/49/95otrte=5/M45km3hi)/er Constraint: (0.202mm < 0.254mm) Between Pad Q1-4(49.875mm,56.5mm) on Top Layer And Pad
QihB(4Br9Soide,5MaishnShi)ver Constraint: (0.047mm < 0.254mm) Between Pad Q1-5(49.875mm,57.15mm) on Top Layer And Pad
Q1hb(APB\$5tder,5/Va8kn9ti)ver Constraint: (0.187mm < 0.254mm) Between Pad Q1-7(48.95mm,57.45mm) on Top Layer And Pad
Q1hph(Abp95otteFM45kn9h)ver Constraint: (0.047mm < 0.254mm) Between Pad Q2-1(59.075mm,57.884mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-2(59.075mm,57.234mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-3(59.075mm,56.584mm) on Top Layer And Pad
Qahift@msotile5@haskr\$liver Constraint: (0.202mm < 0.254mm) Between Pad Q2-3(59.075mm,56.584mm) on Top Layer And Pad
Mantom source and a variety source of the constraint: (0.262mm < 0.254mm) Between Pad Q2-4(60.925mm, 56.584mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-4(60.925mm,56.584mm) on Top Layer And Pad
Qaarkomsofile5 Maskr\$liver Constraint: (0.202mm < 0.254mm) Between Pad Q2-4(60.925mm,56.584mm) on Top Layer And Pad
Qaab(QamsotteeAmaskr\$liver Constraint: (0.047mm < 0.254mm) Between Pad Q2-5(60.925mm,57.234mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad Q2-7(60mm,57.534mm) on Top Layer And Pad Q2-8(60mm,56.494mm) or
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q3-1(10.4mm,30.525mm) on Top Layer And Pad
QiànithQSolde Mask Silver constraint: (0.047mm < 0.254mm) Between Pad Q3-2(11.05mm,30.525mm) on Top Layer And Pad
Mana (unity Sout) 30 Mask (uni
Qihiri(Un7 Soute 3 Maskmoni) er Constraint: (0.202mm < 0.254mm) Between Pad Q3-3(11.7mm,30.525mm) on Top Layer And Pad
Man Mich Solde Mask Style Constraint: (0.20211111 \ 0.202111111 \ 0.202111111 \ 0.20211111 \ 0.20211111 \ 0.20211111 \ 0.20211111 \ 0.202111111 \ 0.20211111 \ 0.20211111 \ 0.20211111 \ 0.20211111 \ 0.202111111 \ 0.202111111 \ 0.20211111 \ 0.20211111 \ 0.20211111 \ 0.20211111 \
Mantifuln's Soldes Mask (Single) Constraint: (0.047mm < 0.254mm) Between Pad Q3-4(11.7mm,32.375mm) on Top Layer And Pad
Qihiri(Un75otte6M45km3hi)er Constraint: (0.202mm < 0.254mm) Between Pad Q3-4(11.7mm,32.375mm) on Top Layer And Pad
Qihafi(tih7SottesMaskrotik)er Constraint: (0.202mm < 0.254mm) Between Pad Q3-5(11.05mm,32.375mm) on Top Layer And Pad
Mahintan Solves (Nash Shiper Constraint: (0.047mm < 0.254mm) Between Pad Q3-7(10.75mm,31.45mm) on Top Layer And Pad
Man (chin/ Soite & Mask Sin/Shi)ver Constraint: (0.047mm < 0.254mm) Between Pad Q4-1(26.975mm, 30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-2(27.625mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-3(28.275mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q4-3(28.275mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2021mm < 0.254mm) Between Pad Q4-4(28.275mm, 32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-4(28.275mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q4-4(28.275mm, 32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.20211111 \cdot 0.202411111) Between Pad Q4-5(27.625mm, 32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-7(27.325mm,31.62mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad Q5-1(41.115mm,66.966mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-1(41.115mm,67.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-2(41.115mm, 07.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-5(38.385mm,67.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.1961mm < 0.254mm) Between Pad U1-1(30.325mm,11mm) on Top Layer And Pad U1-17(31.75mm,10.25mm)
Minimum Solder Mask Sliver Constraint: (0.0254mm) Between Pad U1-1(30.325mm,11mm) on Top Layer And Pad U1-2(30.325mm,10.5mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad
Minimum Soider Mask Silver Constraint: (0.047mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad  Minimum Soider Mask Silver Constraint: (0.022mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad
Minimitation Somer Maskinshiper Constraint: (0.022mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad U1-9(33.175mm,9.5mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-11(33.175mm,10.5mm) on Top Layer And Pad U1-9(35.175mm).
Winimum Soider Mask Silver Constraint: (0.047mm < 0.254mm) Between Pad U1-11(33.175mm,10.5mm) on Top Layer And Pad  Winita(#3.575mm,10.5mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-12(33.175mm,11mm) on Top Layer And Pad
Minimum Soider Mask Silver Constraint: (0.0224mm < 0.254mm) Between Pad U1-12(33.175mm) on Top Layer And Pad  Minim (0.047mm < 0.254mm) Between Pad U1-13(32.5mm,11.675mm) on Top Layer And Pad
U1-14(32mm,11.675mm)

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Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-13(32.5mm,11.675mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-14(32mm,11.675mm) on Top Layer And Pad
Minita(21). Solute 1 Waskinstower Constraint: (0.022mm < 0.254mm) Between Pad U1-14(32mm,11.675mm) on Top Layer And Pad
Minity (2th. Statuter, Maskinshiver Constraint: (0.047mm < 0.254mm) Between Pad U1-15(31.5mm, 11.675mm) on Top Layer And Pad
Minife ใส่บริเพาร์โทย Constraint: (0.022mm < 0.254mm) Between Pad U1-15(31.5mm,11.675mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-16(31mm,11.675mm) on Top Layer And Pad
Minity (2th. 35thder, Maskinstower Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm, 10.25mm) on Top Layer And Pad
Minal(1000) Stortder, Maskn81)ver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-3(30.325mm,10mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-4(30.325mm,9.5mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-5(31mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-6(31.5mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-7(32mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-8(32.5mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-9(33.175mm,9.5mm
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-2(30.325mm,10.5mm) on Top Layer And Pad U1-3(30.325mm,10mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-3(30.325mm,10mm) on Top Layer And Pad U1-4(30.325mm,9.5mm) dr
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-5(31mm,8.825mm) on Top Layer And Pad U1-6(31.5mm,8.825mm) or
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-6(31.5mm,8.825mm) on Top Layer And Pad U1-7(32mm,8.825mm) or
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-7(32mm,8.825mm) on Top Layer And Pad U1-8(32.5mm,8.825mm) or
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-1(30.325mm,18.25mm) on Top Layer And Pad
Mần Tổm (ያስ. ፕሬክዴክ ያክንስ er Constraint: (0.047mm < 0.254mm) Between Pad U2-1(30.325mm,18.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-10(33.175mm.17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-10(33.175mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-10(33.175mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-11(33.175mm,17.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-11(33.175mm,17.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-12(33.175mm,18.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-13(32.5mm,18.925mm) on Top Laver And Pad
M2n/M4/22rSovid/8-M25xN9/ver Constraint: (0.022mm < 0.254mm) Between Pad U2-13(32.5mm,18.925mm) on Top Layer And Pad
Mæin/(ፊክ. ሜሪክሊክ / Masmstilver Constraint: (0.047mm < 0.254mm) Between Pad U2-14(32mm,18.925mm) on Top Layer And Pad
M2n1f5(2nt Sworte 1 8/925tr 8/twer Constraint: (0.022mm < 0.254mm) Between Pad U2-14(32mm,18.925mm) on Top Layer And Pad U2-17(31.75mm,17.5mm
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-15(31.5mm.18.925mm) on Top Laver And Pad
Manha (ជារាទ្ធិសេស្ត្រាម្ចេក Constraint: (0.022mm < 0.254mm) Between Pad U2-15(31.5mm,18.925mm) on Top Layer And Pad
M2nitri(ብነስ: 35onder, M7a5th 8ti)ver Constraint: (0.022mm < 0.254mm) Between Pad U2-16(31mm,18.925mm) on Top Layer And Pad U2-17(31.75mm,17.5mm
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm, 17.5mm) on Top Layer And Pad
Mahara Strong Master Master Shower Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad
Maaa (የፈርስ 3 Stotoler, Waster Stroker Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm, 17.5mm) on Top Layer And Pad
M2n4(30n3 25thter), Ma3&15thter) Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-5(31mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-6(31.5mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm, 17.5mm) on Top Layer And Pad U2-7(32mm, 16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-8(32.5mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad
Man Statuter, Mastarshiver Constraint: (0.047mm < 0.254mm) Between Pad U2-2(30.325mm,17.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-3(30.325mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-5(31mm,16.075mm) on Top Layer And Pad U2-6(31.5mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-6(31.5mm,16.075mm) on Top Layer And Pad U2-7(32mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-7(32mm,16.075mm) on Top Layer And Pad U2-8(32.5mm,16.075mm)
on
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